•	
-	-

L	Hits	Search Text	DB	Time stamp
Number				
1	392648	heat with (spreader radiate sink	USPAT;	2003/05/29
		stiffener metal slug lid top cover)	US-PGPUB;	19:28
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	207062	(thincore coreless (thin adj core) thin)	USPAT;	2003/05/29
		with (substrate board pc pcb pb cb	US-PGPUB;	19:33
		(printed adj board))	EPO; JPO;	
]		DERWENT;	
	120050		IBM_TDB	2222 /25 /22
3	139852	(semiconductor flipchip (flip adj chip)	USPAT;	2003/05/29
		ic (integrated adj circuit)) and	US-PGPUB; EPO; JPO;	19:32
		(packaging package)		
			DERWENT; IBM TDB	
4	2882	(heat with (spreader radiate sink	USPAT;	2003/05/29
•	2002	stiffener metal slug lid top cover)) and	US-PGPUB;	19:34
		((thincore coreless (thin adj core) thin)	EPO; JPO;	13.0.
		with (substrate board pc pcb pb cb	DERWENT;	
		(printed adj board))) and ((semiconductor	IBM TDB	
		flipchip (flip adj chip) ic (integrated	_	
		adj circuit)) and (packaging package))		
5	222398	(thincore coreless (thin adj core) thin)	USPAT;	2003/05/29
		with (substrate board pc pcb pb cb	US-PGPUB;	19:34
	1	carrier (printed adj board))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	3128	(heat with (spreader radiate sink	USPAT;	2003/05/29
		stiffener metal slug lid top cover)) and	US-PGPUB;	19:34
		((thincore coreless (thin adj core) thin)	EPO; JPO;	
		with (substrate board pc pcb pb cb	DERWENT;	
		carrier (printed adj board))) and ((semiconductor flipchip (flip adj chip)	IBM_TDB	
	:	ic (integrated adj circuit)) and		
		(packaging package))		·
7	2053	((heat with (spreader radiate sink	USPAT;	2003/05/29
'	2003	stiffener metal slug lid top cover)) and	US-PGPUB;	19:35
		((thincore coreless (thin adj core) thin)	EPO; JPO;	
		with (substrate board pc pcb pb cb	DERWENT;	,
	,	carrier (printed adj board))) and	IBM TDB	
		((semiconductor flipchip (flip adj chip)	_	
		ic (integrated adj circuit)) and		
		(packaging package))) and (Pga pin pins		
		bga ball bump)		